

SG6841SZ

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Highly-Integrated Green-Mode PWM Controller

Qualification Data

Test Standards:

- ? Moisture Sensitivity: 2
- ? Thermal Impedance: 141
- ? Physical Dimensions: SOIC
- ? ESD HBM: 3
- ? ESD MM: 250

Attribute	Value	UOM
General Information		
Device Marking(TOP MARK)	SG6841SZ K&60&4&Z	
Family Code	OGD	
Package Type	SOIC	
Package Description	008, PLASTIC MOLDED, SOIC-8 PKG, NARROW BODY, SMD (S1)	
Pin Count	8	
Maximum Reflow Temperature	260C	
Restriction of Hazardous Substance		
Standard Plating Finish	Matte Sn	
Base Metal/Leadframe Material	Copper,Iron,Zinc,Phosphorus,Silver	
Lead Pitch	1270	
Minimum Lead Spacing	760	
Die Fabrication		
Fabrication Process Identifier	SG6841C	
Package Assembly*		
Plating Finish Layer Thickness	8.0um - 13um	
Thermal Impedance (Theta JA)	141	°C/Watt
Moisture Sensitivity	2	
Electrical Test		
ESD Human Body Model (HBM)	3	V
ESD Machine Model (MM)	250	V

*If an attribute is listed twice, either can be used on the part.